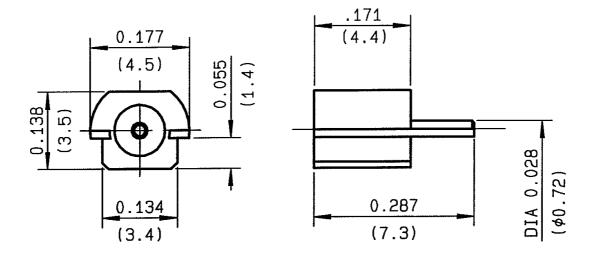
R110.422.100

Series: MMCX



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD OVER NICKEL GOLD OVER NICKEL

Issue: 0422 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



R110.422.100

Series: MMCX

PACKAGING

Standard Unit Other 100 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω Frequency **0-6** GHz

VSŴR AD +

0.000 x F(GHz) Maxi Insertion loss **AD** $\sqrt{F(GHz)}$ dB Maxi

RF leakage **AD** - F(GHz)) dB Maxi - (

Voltage rating 250 Veff Maxi

Dielectric withstanding voltage **500** Veff mini Insulation resistance 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end 10 N mini Axial force – Opposite end 10 N mini Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.390** g

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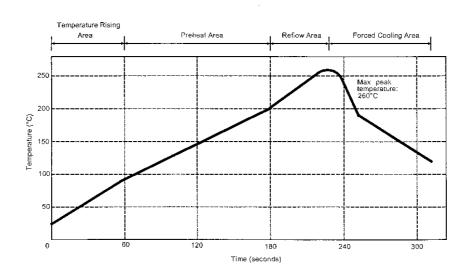
R110.422.100

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SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 microns (0.006 inch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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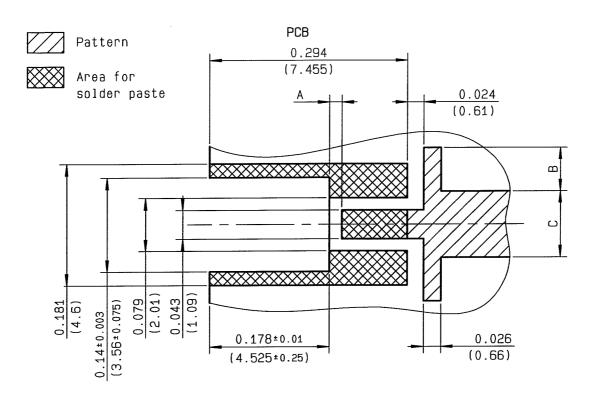
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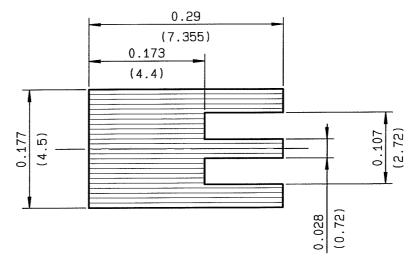
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PCB THICKNESS	Α	В	C
0.031 (0.79)	0.039 (0.99)	-	0.055 (1.4)
0.039 (0.99)	0.035 (0.89)	0.012 (0.3)	0.071 (1.8)
0.063 (1.6)	0.016 (0.41)	0.063 (1.6)	0.11 (2.79)

SHADOW OF MMCX RECEPTACLE FOR VIDEO CAMERA



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